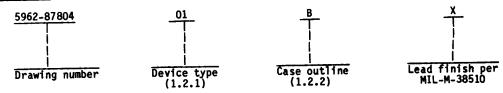
					_					<u>.y</u>										
					L							RE	VIS	ION	S					
					Ľ	LTR	$oldsymbol{\perp}$			DE	SCRI	PTIC	N			DA	TE	AF	PPRO	OVE
					•		•									•	,	ı		
REV			Ι								1						Ι			
PAGE	$oxed{oxed}$		E		Е			E		H				1	L	Н	Ţ	E	Н	7
PAGE REV STATUS	REV		E																	
PAGE REV STATUS	REV PAGE:	s 1	2	3	4	5	6	7	8											
PAGE REV STATUS OF PAGES Defense Electronic	PAGE	S 1	2	3 PA	4 RE0	5 /)	6 Y	7	8		N			 	RY	D	H R	I W		I G
OF PAGES  Defense Electronic Supply Center	PAGE	S 1	PATE	PA	REG	D.	Y Ca	7	8 Ne	in_	N	nis d	rawi	ng is	avail	able fo	or us	e by		1G
PAGE REV STATUS OF PAGES Defense Electronic Supply Center	PAGE	<b>S</b> ]	PATE	PA	4	D.	Y G	ee	ne		aı	nis d I De	rawi: partn	ng is	avail	able fo Agenci	or us	e by		1G
PAGE REV STATUS OF PAGES Defense Electronic Supply Center Deyton, Ohio	PAGE	<b>S</b> 1	chi	ECK	REG V			7	ne		De	nis d I Dep epart	rawin partn ment	ng is nents of D	avail and efense RCUIT	able for Agencies	or us les of	e by the ADV/	ANCE	D
PAGE REV STATUS OF PAGES Defense Electronic Supply Center Dayton, Ohio Original date	PAGE	S 1	chi	ECK	REG			ee	ne		De	nis d I Dep epart	rawin partn ment	ng is nents of D	avail and efense RCUIT	able fo Agenci	or us les of	e by the ADV/	ANCE	D
PAGE REV STATUS OF PAGES Defense Electronic Supply Center Dayton, Ohio Original date	PAGE:	S 1	CHI CHI API	PA WITE CH	The state of the s	B. B.	Y (3)	el En En	ne T.		TI SC	nis d I Dep epart TLE HOTT	rawin partn ment	ng is nents of D ROCII	avail and efens RCUIT AND G	able for Agencies DIG	or us les of ITAL MONOL	e by the ADV/	ANCE	ILIC(
PAGE REV STATUS OF PAGES Defense Electronic Supply Center Dayton, Ohio Original date of drawing:	PAGE:	S 1	CHI CHI	PA	The state of the s	B. B.	Y (3)	el	ne T.	<u>&gt;</u>	TI SC	nis d I Dep epart TLE HOTT	rawin partn ment : MI( KY T	ng is nents of D ROCII	avail and efens RCUIT AND G	able for Agencies	or us les of ITAL MONOL	e by the ADV/	ANCE	ILIC(

<u>DISTRIBUTION STATEMENT A.</u> Approved for public release; distribution is unlimited. **DESC FORM 193 MAY 86** 

- 1. SCOPE
- 1.1 <u>Scope</u>. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices".
  - 1.2 Part number. The complete part number shall be as shown in the following example:



1.2.1 Device type. The device type shall identify the circuit function as follows:

Device type	Generic number	Circuit function
01	54AS21	Dual 4-input positive AND gate

1.2.2 <u>Case outlines</u>. The case outline shall be as designated in appendix C of MIL-M-38510, and as follows:

Outline letter	<u>Case outline</u>
B C D	F-3 (14-lead, 3/16" x 1/4"), flat package D-1 (14-lead, 1/4" x 3/4"), dual-in-line package F-2 (14-lead, 1/4" x 3/8"), flat package C-2 (20-terminal, .350" x .350"), square chip carrier package

1.3 Absolute maximum ratings.

1.4 Recommended operating conditions.

```
Supply voltage (V_{CC}) - - - - - - - - - - - - 4.5 V dc minimum to 5.5 V dc maximum Minimum high level input voltage (V_{IH}) - - - - - 2.0 V dc 0.8 V dc Case operating temperature range (T_{C}) - - - - - - - - - - - - - - 55 °C to +125 °C
```

- 1/ Must withstand the added PD due to short circuit test (e.g., Ios).
- When a thermal resistance for this case is specified in MIL-M-38510, appendix C, that value shall supersede the value specified herein.

MILITARY DRAWING	SIZE A	14933	DWG NO	5962-878	04
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO		REV		PAGE	2

## 2. APPLICABLE DOCUMENTS

2.1 Government specification and standard. Unless otherwise specified, the following specification and standard, of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

## **SPECIFICATION**

MILITARY

MIL-M-38510

Microcircuits, General Specification for.

STANDARD

MILITARY

MIL-STD-883

Test Methods and Procedures for Microelectronics.

(Copies of the specification and standard required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

- 2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.
  - 3. REQUIREMENTS
- 3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.
- 3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.
- 3.2.1 Terminal connections and logic diagram. The terminal connections and logic diagram shall be as specified on figure 1.
  - 3.2.2 Truth table. The truth table shall be as specified on figure 2.
  - 3.2.3 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.
- 3.3 Electrical performance characteristics. Unless otherwise specified, the electrical performance characteristics are as specified in table I and apply over the full recommended case operating temperature range.
- 3.4 Marking. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the part number listed in 1.2 herein. In addition, the manufacturer's part number may also be marked as listed in 6.4 herein.
- 3.5 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in 6.4. The certificate of compliance submitted to DESC-ECS prior to listing as an approved source of supply shall state that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.
- 3.6 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.

MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO	SIZE A	14933	DWG NO. 5962-87804
		REV	PAGE 3

	_ <del></del>	T	1	Lii	nts	
Test	Symbol	Conditions -55°C < T <sub>C</sub> < +125°C unless otherwise specified	Group A  subgroups  	Min	Max	Unit
Low level output voltage	V <sub>OL</sub>	V <sub>CC</sub> = 4.5 V, I <sub>OL</sub> = 20 mA   V <sub>IN</sub> = 0.8 V or 2.0 V	1,2,3	     	.5	٧
High level output voltage	Voн	V <sub>CC</sub> = 4.5 V, I <sub>OH</sub> = -2 mA   V <sub>IN</sub> = 0.8 V or 2.0 V	1,2,3	2.5		٧
Input clamp voltage	V <sub>IC</sub>		1		  -1.2 	V   
High level input current	I <sub>IH1</sub>		1,2,3	1	20	   μ <b>Α</b> 
	I <sub>IH2</sub>	V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = 7.0 V	1,2,3	   	100	Ι   μΑ 
Low level input current	IIL	V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = 0.4 V	1,2,3		-500	l   μ <b>A</b> 
Short circuit output current	I <sub>10</sub>	V <sub>CC</sub> = 5.5 V, V <sub>OUT</sub> = 2.25 V	1,2,3	-30 	  -112 	mA   mA
Supply current	ICCH	V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = 4.5 V	1,2,3		4.6	mA
	ICCL	V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = 0.0 V	1,2,3		12	   mA 
Functional tests	İ	  See 4.3.1c	7	   		
Propagation delay time, A, B, C, or D to Y	i itpLH, itpHL	V <sub>CC</sub> = 5.0 V, R <sub>L</sub> = 500Ω  C <sub>L</sub> = 50 pF	9   10,11	1 1	7   10	ns

<sup>1/</sup> The output conditions have been chosen to produce a current that closely approximates one-half of the true short circuit output current,  $I_{OS}$ .

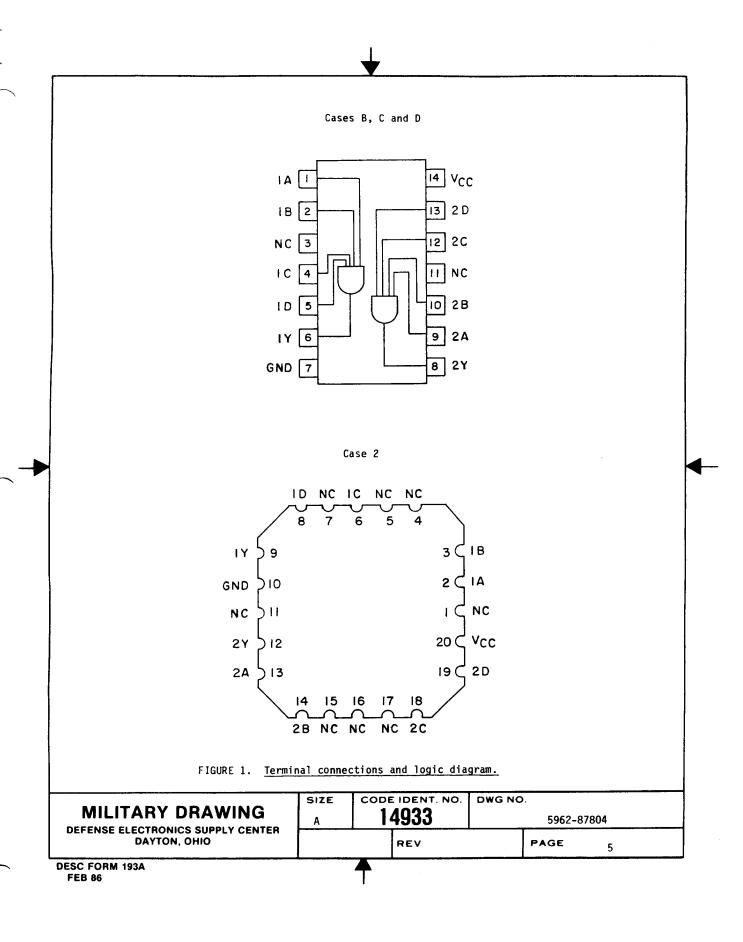
<sup>4.1</sup> Sampling and inspection. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).

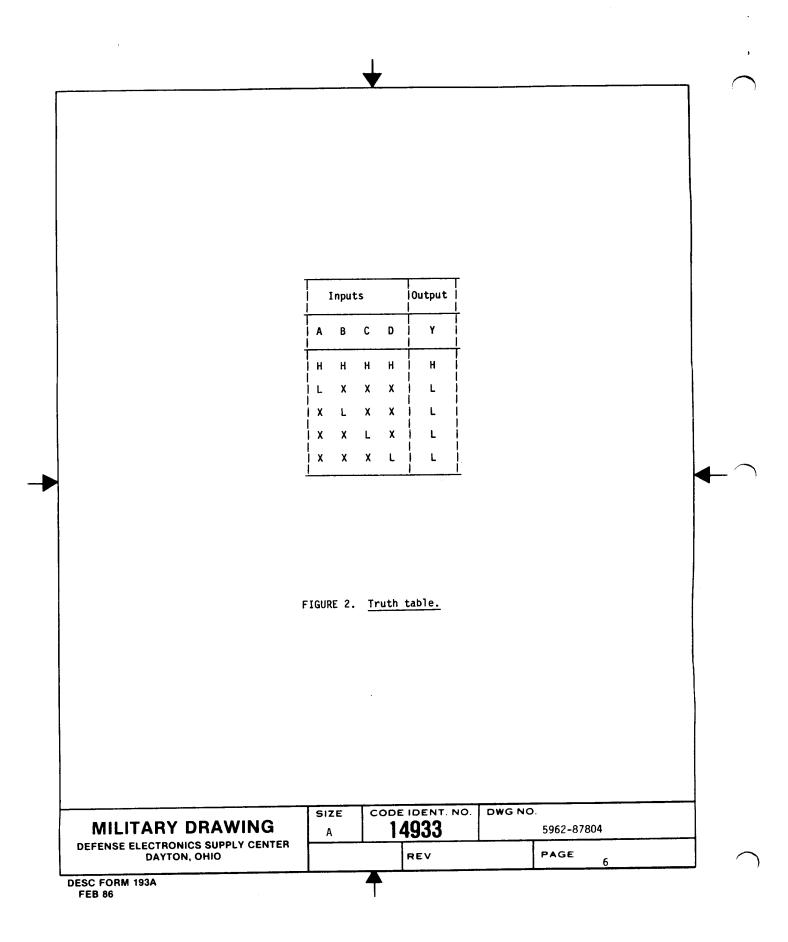
MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO	SIZE A	14933	DWG NO. 5962-87804		
		REV	PAGE 4		

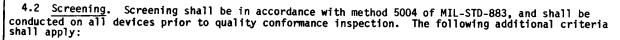
<sup>3.7</sup> Notification of change. Notification of change to DESC-ECS shall be required in accordance with MIL-STD-883 (see 3.1 herein).

<sup>3.8</sup> Verification and review. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

<sup>4.</sup> QUALITY ASSURANCE PROVISIONS







- a. Burn-in test (method 1015 of MIL-STD-883).
  - Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
  - (2)  $T_A = +125^{\circ}C$ , minimum.
- b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
- 4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method  $\overline{5005}$  of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
  - 4.3.1 Group A inspection.
    - a. Tests shall be as specified in table II herein.
    - b. Subgroups 4, 5, 6, and 8 in table I, method 5005 of MIL-STD-883 shall be omitted.
    - c. Subgroup 7 tests shall verify the truth table.
  - 4.3.2 Groups C and D inspections.
    - a. End-point electrical parameters shall be as specified in table II herein.
    - b. Steady-state life test (method 1005 of MIL-STD-883) conditions:
      - Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
      - (2)  $T_A = +125^{\circ}C$ , minimum.
      - (3) Test duration: 1,000 hours, except as permitted by appendix B of MIL-M-38510 and method 1005 of MIL-STD-883.

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups     (per method     5005, table I)
Interim electrical parameters (method 5004)	
Final electrical test parameters   (method 5004) 	1*,2,3,9
Group A test requirements   (method 5005) 	1,2,3,7,9,   10,11
Groups C and D end-point   electrical parameters   (method 5005)	1,2,3

\*PDA applies to subgroup 1.

MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO

SIZE
A
14933

5962-87804

REV
PAGE 7

- 5. PACKAGING
- 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.
- 6. NOTES
- 6.1 Intended use. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.
- 6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, Ohio 45444, or telephone 513-296-5375.
- 6.4 Approved source of supply. An approved source of supply is listed herein. Additional sources will be added as they become available. The vendor listed herein has agreed to this drawing and a certificate of compliance (see 3.5 herein) has been submitted to DESC-ECS.

Military drawing part number	Vendor     CAGE     number	Vendor similar part number <u>1</u> /
5962-8780401BX	01295	SNJ54AS21WA
5962-8780401CX	01295	SNJ54AS21J
5962-8780401DX	01295	SNJ54AS21W
5962-87804012X	01295	SNJ54AS21FK

1/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE number

01295

Vendor name and address

Texas Instruments, Inc. P.O. Box 6448 Midland, TX 79701

MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO	SIZE	14933	DWG NO. 5962-87804
		REV	PAGE 8